

Chokes for Power Lines

Material Data Sheet

			-	-)	
Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Manganese-zinc ferrite	100	12645-49-7	52.9	
	Polymer	2C	Epoxy (EP)	100	25068-38-6	1.1	
	Metal	1C	Cu	100	7440-50-8	40.0	
	Thermoplastic	2A	Polyester-imide (THEIC)	50	839-90-7	0.9	
			Polyamide-imide (PAI)	50	31957–38–7	0.9	
Encapsulation and Mounting	Thermoplastic	2A	Polycarbonate (PC)	89.8	25971-63-5		
			Glass fiber	10	65997-17-3	4.1	
			PFBS	0.2	29420-49-3	1	
	Polymer	2A	Polyethyleneterephthalate (PET)	100	25038-59-9	0.8	
	Polymer	2A	Polyacrylate	100	37325-11-4		Х
Termination	Metal	1C	Sn	100	7440-31-5	0.1	
Label	Polymer	2C	Polyethylentherephthalate (PET)	100	25038-59-9	0.1	
	Polymer	2C	Acrylic resin	100	37325-11-4		Х
		•		•	Sum in total:	100.0	
Size W x L x H [max. in mm] Ø 62x39	Weight [approx. in g] 203	Part Numbers B82747\$4253A040 B82767\$4193N030	mm] [appro	ox. in g]	art Numbers 767\$4253N030		

Size W x L x H	Weight	Part Numbers	Size W x L x H [max. in	Weight	Part Numbers
[max. in mm]	[approx. in g]		mm]	[approx. in g]	
Ø 62x39	203	B82747S4253A040	Ø 60 x 38	210	B82767S4253N030
Ø 60x38	222	B82767S4193N030			
Ø 60x38	205	B82767S4263N030			

Contact	Dr. Johann Reindl, MAG EPQM			
Division	TDK Electronics AG, Magnetics Business Group (MAG)			
Address	Rosenheimer Strasse 116b, 81669 Munich			
	Tel: +49 89 54020 3030	mailto:		
		johann.reindl@tdk-electronics.tdk.com		

^{*)} others: not declarable or prohibited substances acc. GADSL

Important remarks:

- The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.
- This Material Data Sheet contains typical values of the respective products set forth 2) herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid □ not valid)

☑ no exemptions;

□ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

☐ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

☐ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

🗆 Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher:

☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

☐ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages:

☐ Other Exemption than above

^{**)} typical mass percentage of substance